## Specifications

| Drawing No. | UKY1C-H1-16B33-00[40] $1 / 9$ |
| :---: | :---: |
| Issued Date. | Nov.25,2016 |

## TO: Microchip Corporation

Note: In case of specification change, KYOCERA Part Number also will be changed.

| Product Name | Quartz Crystal |
| :---: | :---: |
| Product Model | CX5032GA |
| Frequency | 8000 kHz |
| Customer Part Number | - |
| Customer Specification Number | - |
| KYOCERA Part Number |  |
| Remarks RoHS Compliant, MSL 1 |  |
| AEC-Q200 Compliant |  |

Customer Acceptance

| Accept Signature | Approved Date |  |
| :---: | :---: | :---: |
|  |  |  |
|  | Department |  |
|  |  |  |

## Seller

KYOCERA Crystal Device Corporation
(Sales Division)
6 Takeda Tobadono-cho, Fushimi-ku, Kyoto
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TEL. No. 075-604-3500
FAX. No. 075-604-3501

Manufacturer
KYOCERA Crystal Device Corporation
Crystal Units Division
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999-3701 Japan
TEL. No. 0237-43-5611
FAX. No. 0237-43-5615

| Design Department | Quality Assurance | Approved by | Examination by | Issued by |
| :--- | :---: | :--- | :--- | :--- |
| KYOCERACrysta Device Corporation <br> Crystal Units Engineeing Section <br> Crystal Units Division | W.Muraoka | H. Shoji | A.lto | M.Hashimoto |

## Revision History

| Rev.No. | Description of revise | Date | Approved by | Examination by | Issued by |
| :---: | :--- | :---: | :---: | :---: | :---: |
| $\mathbf{1}$ | First Edition | Nov.25,2016 | H. Shoji | A.to | M.Hashimoto |
|  |  |  |  |  |  |
|  |  |  |  |  |  |

## 1. APPLICATION

This specification sheet is applied to quartz crystal "CX5032GA08000HOKPS02"

## 2. KYOCERA PART NUMBER

## CX5032GA08000H0KPS02

## 3. RATINGS

| Items | SYMB. | Rating | Unit | Remarks |
| :---: | :---: | :---: | :---: | :---: |
| Operating Temperature | Topr | -40 to +85 | ${ }^{\circ} \mathrm{C}$ |  |
| Storage Temperature Range | Tstg | -40 to +150 | ${ }^{\circ} \mathrm{C}$ |  |

## 4. CHARACTERISTICS

## ELECTRICAL CHARACTERISTICS

| Items | Electrical Specification |  |  |  |  | Test Condition | Remarks |
| :---: | :---: | :---: | :---: | :---: | :---: | :---: | :---: |
|  | SYMB. | Min. | Typ. | Max. | Unit |  |  |
| Mode of Vibration |  | Fundamental |  |  |  |  |  |
| Nominal Frequency | F0 |  | 8 |  | MHz |  |  |
| Nominal Temperature | $\mathrm{T}_{\text {NOM }}$ |  | +25 |  | ${ }^{\circ} \mathrm{C}$ |  |  |
| Load Capacitance | CL | 12.0 |  |  | pF |  |  |
| Frequency <br> Tolerance | df/F | -30.0 |  | +30.0 |  | $+25 \pm 3^{\circ} \mathrm{C}$ |  |
| Frequency Temperature Characteristics | df/F | -50.0 |  | +50.0 | PPM | -40 to $+85^{\circ} \mathrm{C}$ |  |
| Frequency Aging Rate |  | -5.0 |  | +5.0 |  | $1^{\text {st }}$ year | $+25 \pm 3^{\circ} \mathrm{C}$ |
| Equivalent Series Resistance | ESR |  |  | 300 | $\Omega$ |  |  |
| Drive Level | Pd | 0.01 |  | 500 | $\mu \mathrm{W}$ |  |  |
| Insulation Resistance | IR | 500 |  |  | $\mathrm{M} \Omega$ | 100V(DC) |  |

## 5. Measurement Condition

| 5.1 Frequency measurement |  |
| :--- | :--- |
| Measuring instrument | $:$ PI-Network Test Fixture |
| Load Capacitance | $: 12.0 \mathrm{pF}$ |
| Drive Level | $: 10 \mu \mathrm{~W}$ |
| 5.2 Equivalent series resistance $($ ESR $)$ measurement |  |
| Measuring instrument | $:$ PI-Network Test Fixture |
| Load Capacitance | $:$ Series |
| Drive Level | $: 10 \mu \mathrm{~W}$ |

## 6. APPEARANCES, PHYSICAL DIMENSION <br> OUTLINE DIMENSION (not to scale)



| (A) | Terminal | W-Ni-Au(Pb-Free) |
| :--- | :--- | :--- |
| (B) | CAP | CERAMICS(BLACK) |
| (C) | BASE | CERAMICS(BLACK) |
| (D) | GLASS | LOWTEMPERATURE GLASS |


|  | MARKING | NOTE |
| :--- | :--- | :--- |
| (1) | NOMINAL FREQUENCY | (5 DIGITS MAX) UNIT: kHz |
| (2) | IDENTIFICATION | - |
| (3) | DATE CODE | YEAR $\cdots \cdots$ LAST 1 DIGIT of YEARAND WEEK <br> EXAMPLE $\cdots \cdot$ Jan. 1,2016 $\rightarrow 601$ |
| (4) | MANUFACTURING <br> LOCATION | Y : Japan (Yamagata) <br> T : Thailand |
| The font of marking is reference. |  |  |

## 7. RECOMMENDED LAND PATTERN (not to scale)



Unit : mm

## 8. TAPING \& REEL

8.1 Carry tape dimension


### 8.3 Taping specification

1. Material of the carrier tape shall be A -PET or PS (ESD)
2. The seal tape shall not cover the sprocket holes. And not protrude from the carrier tape.
3. Tensile strength of the tape: 10 N or more.
4. The number of lack is $0.1 \%$ of 1 reel total part number (the number of the table letters) or the part following whose 1 either is big. (But, the thing which lack of the continuance is not in.)
5 . The $R$ of the corner without designation is $0.3 R$ MAX.
5. Misalignment between centers of the cavity and sprocket hole shall be 0.05 mm or less.
6. Peeling force of the seal tape (Peeling speed $300 \mathrm{~mm} / \mathrm{min}$.): 0.1 to 1.0 N .
7. Cumulative pitch error of feed hole : 50 pitch $\rightarrow \pm 0.3 \mathrm{~mm}$
8. The marking on parts is not fixed its direction, its electrical characteristic is equal.


### 8.4 Reel specifications


$\phi 180 \operatorname{Reel}(1,000 \mathrm{pcs}$. Max.)

| Symbol | A | B | C | D |
| :--- | :---: | :---: | :---: | :---: |
| Dimension | $\phi 180$ | $\phi 60$ | $\phi 13$ | $\phi 21$ |
| Symbol | E | W |  |  |
| Dimension | 2.0 | 13.0 |  |  |

## 9.Enviromental requirements

(Reference: AEC-Q200 Rev. D. The solder used by examination is hereafter set to $\mathrm{Sn}-3 \mathrm{Ag}-0.5 \mathrm{Cu}$.) After following test, Frequency applies to each item and $\mathrm{CI}, \pm 20 \%$ or $5 \Omega$ of large value.

| No | Stress | Reference | Additional Requirements |
| :---: | :---: | :---: | :---: |
| 9.1 | High Temperature Exposure (Storage) | MIL-STD-202 <br> Method 108 | 1000 hrs. at rated operating temperature (e.g. $85^{\circ} \mathrm{C}$ part can be stored for 1000 hrs at $85^{\circ} \mathrm{C}$. Same applies for $125^{\circ} \mathrm{C}$ ). Unpowered. <br> Measurement at $24 \pm 4$ hours after test conclusion. |
| 9.2 | Temperature Cycling | JESD22 <br> Method JA-104 | 1000 cycles ( $-40^{\circ} \mathrm{C}$ to $125^{\circ} \mathrm{C}$ ) Note: If $85^{\circ} \mathrm{C}$ part the 1000 cycles will be at that temperature rating. <br> Measurement at $24 \pm 4$ hours after test conclusion. <br> 30 min maximum dwell time at each temperature extreme. 1 min. maximum transition time. |
| 9.3 | Biased Humidity | MIL-STD- 202 <br> Method 103 | 1000 hours $85^{\circ} \mathrm{C} / 85 \%$ RH. Rated VDD applied with 1 MW and inverter in parallel, 2 X crystal CL capacitors between each crystal leg and GND. <br> Measurement at $24 \pm 4$ hours after test conclusion. |
| 9.4 | Operational Life | MIL-STD- 202 <br> Method 108 | Note: $1000 \mathrm{hrs} @ 125^{\circ} \mathrm{C}$. If $85^{\circ} \mathrm{C}$ part will be tested at that temperature. Rated VDD applied with 1 MW and inverter in parallel, 2 X crystal CL capacitors between each crystal leg and GND. <br> Measurement at $24 \pm 4$ hours after test conclusion. |
| 9.5 | Terminal Strength (Leaded) | MIL-STD- 202 Method 211 | Test leaded device lead integrity only. Conditions: A $(227 \mathrm{~g}), \mathrm{C}(227 \mathrm{~g})$. |
| 9.6 | Resistance to Solvents | MIL-STD- 202 <br> Method 215 | Note: Also aqueous wash chemical - OKEM clean or equivalent. Do not use banned solvents. |
| 9.7 | Mechanical Shock | $\begin{array}{\|l\|} \hline \text { MIL-STD-202 } \\ \text { Method } 213 \\ \hline \end{array}$ | Figure 1 of Method 213. Condition C |
| 9.8 | Vibration | MIL-STD-202 <br> Method 204 | 5 g's for 20 minutes 12 cycles each of 3 orientations. Note: Use 8"X5" PCB .031" thick with 7 secure points on one 8 " side and 2 secure points on corners of opposite sides. Parts mounted within 2" from any secure point. Test from $10-2000 \mathrm{~Hz}$. |
| 9.9 | Resistance to Soldering Heat | MIL-STD-202 <br> Method 210 | Condition B No pre-heat of samples. Note: Single Wave solder - Procedure 1 with solder within 1.5 mm of device body for Leaded. Procedure 1 except $230^{\circ} \mathrm{C}$ and immerse only to level to cover terminals for SMD. |
| 9.10 | Solder ability | J-STD-002 | For both Leaded \& SMD. Electrical Test not required. Magnification 50 X . Conditions: <br> Leaded: Method A @ $235^{\circ} \mathrm{C}$, category 3. <br> SMD: a) Method B, 4 hrs @ $155^{\circ} \mathrm{C}$ dry heat @ $235^{\circ} \mathrm{C}$ <br> b) Method B @ $215^{\circ} \mathrm{C}$ category 3 . <br> c) Method D category 3 @ $260^{\circ} \mathrm{C}$. |
| 9.11 | Flammability | UL-94 | V-0 or V-1 Acceptable |
| 9.12 | Board Flex | AEC Q200-005 | 60 sec minimum holding time. |
| 9.13 | Terminal Strength(SMD) | AEC Q200-006 | - |


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| :--- | :--- |

## 10.Cautions for use

(1) Soldering upon mounting

There is a possibility to influence product characteristics when Solder paste or conductive glue comes in contact with product lid or surface.
(2) When using mounting machine

Please minimize the shock when using mounting machine to avoid any excess stress to the product.
(3) Conformity of a circuit

We strongly recommend to make sure that Negative resistance (Gain) of IC is designed to be 10 times the ESR (Equivalent Series Resistance) of crystal unit.
(4) After making the Quartz Crystal mount on a printed circuit board, if it is required to devide the printed circuit board into another one, use it with attentive confirmation so that a warp cased by this dividing might not affect any damage. When designing a printed circuit board as well as handling the mounting As much as possible. The quartz crystal shall be passed through the reflow furnace. Then it shall be subjected to standard atmospheric conditions, after which cleaning shall be made.

## 11.Storage conditions

Please store product in below conditions, and use within 6 months.
Temperature +18 to $+30^{\circ} \mathrm{C}$, and Humidity of 20 to $70 \%$ in the packaging condition.

## 12. Manufacturing location

Kyocera Crystal Device Corporation / Japan(Yamagata)
Kyocera Crystal Device (Thailand) Co., Ltd / Thailand(Lamphun)

## 13. Quality Assurance

Kyocera Crystal Device Quality Assurance Division

## 14. Quality guarantee

In case when Kyocera Crystal Device Corporation rooted failure occurred within 1year after its delivery, substitute product will be arranged based on discussion. Quality guarantee of product after 1year of its delivery is waivered.

## 15.Others

In case of any questions or opinions regarding the Specification, please have it in written manner within 45 days after issued date.

